# Active metal brazing of Al<sub>2</sub>O<sub>3</sub> to Kovar<sup>®</sup> (Fe–29Ni–17Co wt.%) using Copper ABA<sup>®</sup> (Cu–3.0Si–2.3Ti–2.0Al wt.%)

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## Abstract

The application of an active braze alloy (ABA) known as Copper ABA<sup>®</sup> (Cu–3.0Si–2.3Ti–2.0Al wt.%) to join  $Al_2O_3$  to Kovar<sup>®</sup> (Fe–29Ni–17Co wt.%) has been investigated. This ABA was selected to increase the operating temperature of the joint beyond the capabilities of typically used ABAs such as Ag–Cu–Ti-based alloys.

Silica present as a secondary phase in the  $AI_2O_3$  at a level of ~5 wt.% enabled the ceramic component to bond to the ABA chemically by forming a layer of  $Si_3Ti_5$  at the  $ABA/AI_2O_3$  interface. Appropriate brazing conditions to preserve a near-continuous  $Si_3Ti_5$  layer on the  $AI_2O_3$  and a continuous  $Fe_3Si$  layer on the Kovar<sup>®</sup> were found to be a brazing time of  $\leq 15$  min at 1025 °C or  $\leq 2$  min at 1050 °C. These conditions produced joints that did not break on handling and could be prepared easily for microscopy. Brazing for longer periods of time, up to 45 min, at these temperatures broke down the  $Si_3Ti_5$  layer on the  $AI_2O_3$ , while brazing at  $\geq 1075$  °C for 2–45 min broke down the  $Fe_3Si$  layer on the Kovar<sup>®</sup> significantly. Further complications of brazing at  $\geq 1075$  °C included leakage of the ABA out of the joint and the formation of a new brittle silicide,  $Ni_{16}Si_7Ti_6$ , at the ABA/Al\_2O\_3 interface.

This investigation demonstrates that it is not straightforward to join Al<sub>2</sub>O<sub>3</sub> to Kovar<sup>®</sup> using Copper ABA<sup>®</sup>, partly because the ranges of suitable values for the brazing temperature and time are quite limited. Other approaches to increase the operating temperature of the joint are discussed.

Keywords: Brazing, Joining, Alumina, Al<sub>2</sub>O<sub>3</sub>, Kovar, Copper ABA.

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## 1. Introduction

Among the current techniques to join ceramics to ceramics and to metals, a plethora of which have been reviewed in [1], active metal brazing is a relatively simple technique. This particular brazing method avoids a separate step of metallising the bonding surface of the ceramic to make it more wettable by a conventional braze alloy, such as the Ag–28Cu wt.% eutectic alloy. This is achieved by incorporating an element into the braze alloy which can react with the ceramic to form a phase over which the liquid braze can spread; the resultant braze alloy is referred to as an active braze alloy (ABA). The majority of studies on the active metal brazing of  $Al_2O_3$  have used ABAs based on the Ag–Cu system with added Ti, typically at a level of about 1 to 5 wt.% Ti [2,3]. Other group IV and V elements such as Zr, Hf and V can also be added to Ag, Cu and Ag–Cu alloys [4,5,6,7], but the resultant binary and ternary ABAs have received far less attention than the Ag–Cu–Ti system.

An application has been identified in which  $Al_2O_3$  is joined to a iron–nickel–cobalt alloy with the composition Fe–29Ni–17Co wt.%, also known as Kovar<sup>®</sup>. The brazing of  $Al_2O_3$  and Kovar<sup>®</sup> using a commonly used commercially available Ag–Cu–Ti-based alloy known as Cusil ABA<sup>®</sup>, with the composition Ag–35.25Cu–1.75Ti wt.%, has been studied in some detail recently [8]. In terms of temperature capability Ag–Cu–Tibased ABAs are not recommended for use above 600 °C because of creep and oxidation of the ABA [9]. In order to increase the maximum operating temperature of a composite containing a  $Al_2O_3$ –Kovar<sup>®</sup> bond, the use of a commercially available Cubased ABA known as Copper ABA<sup>®</sup>, with the composition Cu–3.0Si–2.3Ti–2.0Al wt.%, has been investigated in this work. There are a number of other commercially available high temperature ABAs such as Gold ABA<sup>®</sup> (Au–3.0Ni–0.6Ti wt.%), Nioro<sup>®</sup>-ABA (Au–15.5Ni–0.75Mo–1.75V wt.%) and Gold-ABA-V<sup>®</sup> (Au–0.75Ni– 1.75V wt.%). However, the high gold content in these ABAs makes them very expensive and more suited to specialist high temperature applications.

Copper ABA<sup>®</sup> melts between 958 and 1024 °C, and so a relatively high brazing temperature is required to produce a bond with this braze alloy. This braze alloy is more ductile than Cusil ABA<sup>®</sup>, which may help to accommodate thermally-induced stresses that develop in a joint; elongations for sheets of Copper ABA<sup>®</sup> and Cusil

ABA<sup>®</sup> with equivalent dimensions are reported as 42% and 20%, respectively [10]. Literature on the brazing of various ceramics using Copper ABA<sup>®</sup> is available, such as  $Si_3Ni_4$  brazed to itself with and without various metallic spacers [11–13],  $Y_2O_3$ -stabilised-ZrO<sub>2</sub> brazed to a stainless steel [14] and SiC-fibre-bonded-ceramics (SA-Tyrannohex<sup>TM</sup>) brazed to themselves [15]. No literature on the brazing of Al<sub>2</sub>O<sub>3</sub> using this alloy has been found. There are a number of experimental Cu-based ABAs with additions of Ga and Sn, along with Ti, V or Zr as active element wetting agents [16–18]. The work of Lin et al. [18] shows that Cu–Sn–Ti-based alloys have the potential to spread on Al<sub>2</sub>O<sub>3</sub> and chemically bond to Al<sub>2</sub>O<sub>3</sub>. In their work, the ability to wet Al<sub>2</sub>O<sub>3</sub> using a range of Cu–Sn–Ti-based alloys containing 6–12 wt.% Ti and 21 wt.% Sn was investigated. An addition of 9 wt.% Ti demonstrated the best wetting ability, with contact angles being consistently lower compared to other alloy compositions over a period of 30 min at 900 °C and approaching zero after 25 min.

The objectives of this work have been to determine whether Copper ABA<sup>®</sup> can be used to bond  $Al_2O_3$  to Kovar<sup>®</sup> chemically and, if so, to determine suitable values for various brazing parameters, such as the peak temperature ( $T_p$ ) and time at  $T_p$  ( $\tau$ ). 99.7 and 95 wt.%  $Al_2O_3$  have been used to study the extent to which silica-based secondary phases in the  $Al_2O_3$  participate in the chemical reactions at the ABA/Al\_2O\_3 interface. Joints were brazed at a  $T_p$  between 1025 and 1100 °C for 0–45 min.

#### 2. Experimental

## 2.1. Materials

Copper ABA<sup>®</sup> (Cu–6.3Si–2.8Ti–4.4Al at.%), which melts between 958 and 1024 °C, has been used to join Kovar<sup>®</sup> to 95 and 99.7 wt.%  $Al_2O_3$ . The ABA was supplied by VBC Group Ltd (UK) in foil form, with a thickness of ~65 µm, from which 10 × 5 mm sections were taken for joining. An investigation of the as-received ABA using a scanning electron microscope (SEM) showed that it contained CuSiTi, with a composition measured by energy dispersive X-ray spectroscopy (EDS) of 33Cu–33Si–34Ti at.%, randomly distributed in a solid solution of Si and Al in Cu (92Cu–4Si–4Al at.%), as shown in the back-scattered electron images (BSEIs) given in Figure 1. Si<sub>3</sub>Ti<sub>5</sub>

particles, with a composition of 37Si–61Ti–2Cu at.%, were also found within some of the CuSiTi particles.

Braze joints made with 95 wt.% Al<sub>2</sub>O<sub>3</sub> were compared with joints made with high purity 99.7 wt.% Al<sub>2</sub>O<sub>3</sub>. Manufacturer's data gave the densities of the two ceramics as 3.7 Mg m<sup>-3</sup> and > 3.9 Mg m<sup>-3</sup> respectively, with grain sizes of 3–8 and 3–10  $\mu$ m respectively. Calculated levels of porosity in the two ceramics were 7% and < 2%respectively. Electron microprobe analysis of the bonding surfaces of both Al<sub>2</sub>O<sub>3</sub> ceramics was performed to determine their composition. A Cameca SX-100 (France) electron microprobe operated at 15 kV with a 10 nA electron beam was used in the wavelength-dispersive mode. Calibration of the elements of interest used several mineral standards. The compositions of the ceramics are given in Table 1. The Si in the 95 wt.% Al<sub>2</sub>O<sub>3</sub> was in the form of intergranular amorphous silica and the Zr was in the form of zirconia particles approximately 4 µm in diameter randomly distributed throughout the ceramic. The zirconia might have been incorporated into the Al<sub>2</sub>O<sub>3</sub> during a milling process that employed zirconia grinding media to produce fine Al<sub>2</sub>O<sub>3</sub> powder prior to sintering. Al<sub>2</sub>O<sub>3</sub> in the form of  $10 \times 5 \times 4$  mm plates were brazed to 10  $\times$  5  $\times$  0.5 mm plates of Kovar<sup>®</sup>. Prior to brazing, all of the components of the joints were cleaned separately in an ultrasonic bath of detergent for up to 15 min.

The as-received Kovar<sup>®</sup> was composed of equiaxed grains of various sizes, ranging from ~10 to ~100  $\mu$ m in width, all of which had a face-centered cubic close packed crystal structure with a lattice parameter of a = 3.6 Å measured by X-ray diffraction. Its composition was measured by EDS as Fe–28Ni–17Co at.%.

## 2.2. Brazing process

 $Al_2O_3/Copper ABA^{\ensuremath{\mathbb{R}}}/Kovar^{\ensuremath{\mathbb{R}}}$  joints were prepared in an atmosphere of purified argon, which was established in a horizontal electric furnace (STF 15/450, Carbolite, UK) as described in [3]. Air Products and Chemicals (USA) BIP<sup>(a)</sup> technology was used to purify the argon gas entering the furnace. A heating rate of 10 °C min<sup>-1</sup> was used. The cooling rate was ~15 °C min<sup>-1</sup> between the peak temperature used and ~500 °C, after which it reduced significantly during a furnace cool to room temperature. A pressure of ~4 kPa was applied to all of the joints using a 20 g weight to improve contact across the components.

The combinations of  $T_p$  and  $\tau$  used to braze the two types of  $Al_2O_3$  are given in Table 2. Brazing of 95 wt.%  $Al_2O_3$  was carried out with  $T_p$  ranging from the liquidus temperature of the ABA of 1025 °C up to 1100 °C. For these brazing experiments  $\tau$ varied between 0 and 45 min. The low quantity of secondary phase in 99.7 wt.%  $Al_2O_3$ made it difficult to establish a bond between the  $Al_2O_3$  and the ABA. Consequently, less work was undertaken on the brazing of this ceramic, with  $\tau$  ranging from 0 to 45 min at a  $T_p$  of 1025 °C, as described in Table 2.

## 2.3. Analytical processes

A field emission SEM, Leo 1530 VP, Leo Electron Microscopy - Carl Zeiss<sup>®</sup>, Germany, operated at 20 kV was used to observe the microstructures of joints, before undertaking more detailed examinations of joints by transmission electron microscopy. This microscope was equipped with an energy dispersive spectrometer (INCA-7426, Oxford Instruments<sup>®</sup>, UK). At least four cross-sections of each joint were analysed with this microscope to monitor the homogeneity of the interfacial structures and the chemistry across the joint. A low speed diamond saw was used to cut out crosssections of joints, which were then mounted in acrylic resin at room temperature, polished and coated with a thin layer of carbon before observations were made. It was necessary to mount all joints made with 99.7 wt.% Al<sub>2</sub>O<sub>3</sub> and the joints made with 95 wt.% Al<sub>2</sub>O<sub>3</sub> using a  $T_p \ge 1075$  °C or 1050 °C with  $\tau \ge 15$  min in clear resin before cutting out cross-sections. This is because the Al<sub>2</sub>O<sub>3</sub> typically separated from the ABA while cutting.

A scanning transmission electron microscope (STEM), Tecnai Osiris<sup>T</sup>, FEI, USA, operated at 200 kV was also used to perform elemental analysis using an EDS system (Super-X system, FEI, USA). Thin sections of joints were prepared for STEM analysis using a focused ion beam instrument, FIB, (Helios Nanolab<sup>TM</sup>, FEI, USA). The procedure commonly known as the lift-out technique [19] was used to transfer sections of joints up to  $25 \times 10 \,\mu\text{m}$  to molybdenum grids, or a carbon substrate on a molybdenum grid. These sections were subsequently reduced to a thickness of ~100 nm using the FIB.

Selected area diffraction patterns were collected to determine the crystal structures of phases using a conventional transmission electron microscope (TEM), 200CX,

JEOL<sup>®</sup>, Japan, which was operated at 200 kV. The camera length of this microscope was monitored at regular intervals using an Al thin film, which was supplied by Agar Scientific, UK.

The thicknesses of the reaction layers were measured as a function of  $T_p$  and  $\tau$  from images collected using the SEM; a mean value and  $\pm$  one standard deviation from twenty five measurements are reported.

## 3. Results

## 3.1. Brazing 95 wt.% Al<sub>2</sub>O<sub>3</sub> to Kovar<sup>®</sup>

The microstructure of the joints made with 95 wt.%  $Al_2O_3$  was strongly affected by the  $T_p$  used, particularly the state of the ABA/Al\_2O\_3 interface. Therefore, the microstructures produced at each  $T_p$  used are discussed separately and as a function of  $\tau$ .

## 3.1.1. Brazing 95 wt.% Al<sub>2</sub>O<sub>3</sub> at 1025 °C

BSEIs of cross-sections of 95 wt.% Al<sub>2</sub>O<sub>3</sub>-Kovar<sup>®</sup> joints that were held at 1025 °C for 0 to 45 min are shown in Figure 2. Brazing at this temperature for a nominal 1 s before cooling was sufficient to melt the ABA completely and to bond chemically the ABA to both the  $Al_2O_3$  and Kovar<sup>®</sup>. Typically, one phase was observed at the ABA/Al<sub>2</sub>O<sub>3</sub> interface in the form of a 1.7 µm thick broken layer with a composition of 37Si-61Ti-2Cu at.%. The crystal structure of the particles in this layer was identified by electron diffraction as that of  $Si_{3}Ti_{5}$  (hexagonal,  $P6_{3}/mcm$ , space group 193) with the lattice parameters a = 7.8 Å and c = 5.4 Å; a selection of indexed electron diffraction patterns is shown in Figure 3. The silica in the Al<sub>2</sub>O<sub>3</sub> appears to react with the Ti in the ABA to form Si<sub>3</sub>Ti<sub>5</sub>, which consequently bonds the Al<sub>2</sub>O<sub>3</sub> component chemically to the ABA. Although there is silicon in the molten braze, evidence such as that in Figure 2 shows clearly that Si<sub>3</sub>Ti<sub>5</sub> is only found at the interface with Al<sub>2</sub>O<sub>3</sub> – it is not found within the braze away from the Al<sub>2</sub>O<sub>3</sub> interface. Hence, while the silicon in the braze is able to participate in the formation of Si<sub>3</sub>Ti<sub>5</sub>, the clear evidence is that the interface with the alumina acts as a favourable nucleation site for Si<sub>3</sub>Ti<sub>5</sub>, because otherwise Si<sub>3</sub>Ti<sub>5</sub> would be seen elsewhere in the joint, rather than just at the interface with Al<sub>2</sub>O<sub>3</sub>.

Particles with a composition of 22Cu–7Ni–3Fe–1Co–34Si–33Ti at.% were occasionally observed between the Si<sub>3</sub>Ti<sub>5</sub> layer and the ABA, specifically at regions where the ABA was directly in contact with a large quantity of silica in the Al<sub>2</sub>O<sub>3</sub>, as shown in Figure 4. The crystal structure of these particles was identified by electron diffraction as that of CuSiTi (orthorhombic, *Pnma*, space group 62) with the lattice parameters a = 6.4 Å, b = 3.9 Å and c = 7.4 Å; a selection of indexed electron diffraction patterns is shown in Figure 5. It is apparent that the Cu in the CuSiTi is partially substituted by the chemical elements of the Kovar<sup>®</sup>, particularly Ni and Fe.

In the same joint, four layers were observed near the Kovar<sup>®</sup> at all bonding times. One of these layers is in contact with the Kovar<sup>®</sup>, while the other three layers are separated from this layer by ~2 µm and are in the ABA. The layer on the Kovar<sup>®</sup> is comprised of large particles which extend across the entire width of the layer, ~ 4.5 µm, and are greater than 10 µm in length parallel to the Kovar<sup>®</sup>. Their composition was measured by EDS typically as 57Fe–15Si–12Ni–9Co–4Al–3Cu at.%. This measurement did not vary significantly normal to the Kovar<sup>®</sup>. The crystal structure of these particles was identified by electron diffraction as that of Fe<sub>3</sub>Si (cubic, *Fm*3*m*, space group 225) with the lattice parameter a = 5.9 Å; a selection of indexed electron diffraction patterns is shown in Figure 6. The EDS data suggests that these Fe<sub>3</sub>Si particles can accommodate various elements in a solid solution, particularly Ni and Co. According to the Fe–Ni–Si phase diagram [20], Fe<sub>3</sub>Si can accommodate significant amounts of Ni at ~T<sub>p</sub>, approximately 26 at.% Ni at 1100 °C.

Furthermore, at all bonding times, a layer up to ~2  $\mu$ m thick with a composition of 23Ni–14Fe–14Co–6Cu–23Si–20Ti at.% is separated from the Fe<sub>3</sub>Si layer by a distance of ~2  $\mu$ m. It appears that this layer formed on the Fe<sub>3</sub>Si layer and subsequently broke away into the ABA, because there are some particles with the same composition on the Fe<sub>3</sub>Si layer. A selection of electron diffraction patterns from the particles in this layer is shown in Figure 7. These patterns are consistent with the crystal structure of Ni<sub>16</sub>Si<sub>7</sub>Ti<sub>6</sub> (cubic, *Fm*3*m*, space group 225) with the lattice parameter *a* = 11.8 Å. The composition of this layer is also consistent with Ni<sub>16</sub>Si<sub>7</sub>Ti<sub>6</sub> if it assumed that some of the Ni is substituted by elements of a similar size such as Fe, Co and Cu, and so this phase is referred to as Ni<sub>16</sub>Si<sub>7</sub>Ti<sub>6</sub>.

There is a thin layer adjacent to the Ni<sub>16</sub>Si<sub>7</sub>Ti<sub>6</sub> layer that varies in thickness between ~50 and ~600 nm. The composition of this layer was measured by EDS in the STEM as 32Fe-29Ti-17Si-11Ni-9Co-2Cu at.%. The particles in this layer have the same crystal structure as Fe<sub>2</sub>Ti (hexagonal, *P*6<sub>3</sub>/*mmc*, space group 194) with the lattice parameters a = 5.2 Å and c = 8.8 Å. A selection of indexed electron diffraction patterns from these particles is shown in Figure 8. The EDS data suggests the Fe in Fe<sub>2</sub>Ti is substituted by several elements, particularly Si. The maximum solubility of Si in Fe<sub>2</sub>Ti is estimated at ~26 at.% Si between 800 and 1150 °C [21].

At all bonding times, there is another layer with the composition 14Cu-10Fe-9Ni-2Co-33Si-32Ti at.% adjacent to the Fe<sub>2</sub>Ti layer. This layer is comprised of particles which have the same crystal structure as CuSiTi (orthorhombic, *Pnma*, space group 62) with the lattice parameters a = 6.4 Å, b = 4.0 Å and c = 7.3 Å; a selection of indexed electron diffraction patterns is shown in Figure 9. Some of the particles in this layer have broken away into the ABA, and so appear as individual CuSiTi particles alongside the CuSiTi layer. The extent of the substitution of Cu by Ni and Fe is much higher in these CuSiTi particles compared with the CuSiTi observed at the ABA/Al<sub>2</sub>O<sub>3</sub> interface.

Increasing  $\tau$  to 2 min produced larger Si<sub>3</sub>Ti<sub>5</sub> particles on the Al<sub>2</sub>O<sub>3</sub>, but collectively they still formed a broken layer up to ~2.5 µm wide. The Al<sub>2</sub>O<sub>3</sub> surface was almost completely covered by a layer of Si<sub>3</sub>Ti<sub>5</sub> between 2 and 3 µm thick after brazing for 15 min. The columnar-like shape of some of the Si<sub>3</sub>Ti<sub>5</sub> particles resulted in a large variation in the thickness of this layer. Increasing  $\tau$  to 30 min caused the Si<sub>3</sub>Ti<sub>5</sub> layer to break down, reducing its average thickness to 1.8 µm. Significant breakdown of the Si<sub>3</sub>Ti<sub>5</sub> layer occurred after brazing for 45 min, resulting in the Si<sub>3</sub>Ti<sub>5</sub> particles to separate from each other and also the Al<sub>2</sub>O<sub>3</sub>.

The thickness of the Fe<sub>3</sub>Si layer on the Kovar<sup>®</sup> increases parabolically with time for joints brazed for 2–45 min at a  $T_p$  of 1025 °C, as shown graphically in Figure 10. Additional joints were brazed for 2 min between 1025 and 1100 °C to estimate the activation energy for growth of this layer. However, this was not possible because of two reasons. Firstly, some of the ABA flowed out of a number of joints prepared at 1075 and 1100 °C, which included those brazed for 2 min at these temperatures.

Secondly, the Fe<sub>3</sub>Si layer breaks up slightly at a  $T_p$  between 1075–1100 °C to leave small Fe<sub>3</sub>Si particles in the ABA between the Fe<sub>3</sub>Si layer and the Ni<sub>16</sub>Si<sub>7</sub>Ti<sub>6</sub> layer. As a consequence, the mean thickness of this layer appears to decrease as  $T_p$  increases.

At a  $T_p$  between 1050 and 1075 °C, the mean thickness of the Fe<sub>3</sub>Si layer initially increases as a function of  $\tau$ , and then it reaches a maximum value before reducing. The reduction in the mean thicknesses is mainly caused by the breakdown of the Fe<sub>3</sub>Si layer, which is amplified by increasing  $T_p$ . No significant changes in the composition of the Fe<sub>3</sub>Si layer as a function of  $T_p$  and  $\tau$  were identified, and so this breakdown process does not appear to be a consequence of any change in the composition of this layer.

The layered structure of  $Ni_{16}Si_7Ti_6$ ,  $Fe_2Ti$  and CuSiTi near the ABA/Kovar<sup>®</sup> interface was continuous only in the joint heated to 1025 °C for 2 min. These phases were typically observed in the form of a broken layered structure or a collection of individual particles in joints prepared at higher  $T_p$  or by using longer  $\tau$ . The Fe<sub>2</sub>Ti phase was not always observed in all of the joints brazed at 1025 °C. Instead Ni<sub>16</sub>Si<sub>7</sub>Ti<sub>6</sub> was observed alongside CuSiTi. In other cases, the  $Fe_2Ti$  is difficult to identify from the BSEIs taken because it has a similar average atomic number compared to Ni<sub>16</sub>Si<sub>7</sub>Ti<sub>6</sub> and it is present in small amounts between the Ni<sub>16</sub>Si<sub>7</sub>Ti<sub>6</sub> and CuSiTi. Small fluctuations in the compositions of Ni<sub>16</sub>Si<sub>7</sub>Ti<sub>6</sub> and Fe<sub>2</sub>Ti as a function of  $T_p$  and  $\tau$  were measured, but no conclusive trends were identified. The variations in these compositions could be a result of Ni<sub>16</sub>Si<sub>7</sub>Ti<sub>6</sub> and Fe<sub>2</sub>Ti having a small homogeneity range at temperatures close to the  $T_p$  used. EDS measurements indicate that the amount of Cu in CuSiTi that is substituted by Fe, Ni and Co increases as a function of  $\tau$  at a given  $T_p$ . The Cu in CuSiTi is almost completely substituted using a  $T_p$  of 1075 °C and  $\tau$  of 2 min, to give a typical composition of 3Cu-13Fe-12Ni-8Co-32Si-32Ti at.%. The quantities of Fe, Ni and Co in the ABA varied within the limits of 1–3 at.%, but no conclusive trends could be identified as a function of  $\tau$  at any  $T_p$ . However, the quantities of Al and Si in the ABA significantly decreased at a T<sub>p</sub> of 1075 °C. Before brazing, the quantities of Al and Si were measured at 4 at.% Al and 4 at.% Si. After brazing at 1075 °C, the quantity of Al was typically measured at 2.5 at.% and the amount of Si reduced to a low level, which could not be measured with confidence. These reductions in the amount of Al and Si in the ABA occurred with a significant

microstructural change involving the formation of a new phase  $(Ni_{16}Si_7Ti_6)$  at the ABA/Al<sub>2</sub>O<sub>3</sub> interface; a detailed account of this change is given later in section 3.1.3. The amount of Si reduces to a lower amount than Al, which is likely to be a consequence of Si participating directly in the formation of phases at both the ABA/Al<sub>2</sub>O<sub>3</sub> interface and ABA/Kovar<sup>®</sup> interface, while Al acts a solute in these phases.

## 3.1.2. Brazing 95 wt.% Al<sub>2</sub>O<sub>3</sub> at 1050 °C

Increasing  $T_p$  to 1050 °C produced significant microstructural developments, particularly at the ABA/Al<sub>2</sub>O<sub>3</sub> interface. Breakdown of the Si<sub>3</sub>Ti<sub>5</sub> layer on the Al<sub>2</sub>O<sub>3</sub> occurred much faster and to a further extent compared with brazing at a  $T_p$  of 1025 °C. BSEIs of cross-sections of 95 wt.% Al<sub>2</sub>O<sub>3</sub>–Kovar<sup>®</sup> joints that were held at 1050 °C for 2 to 45 min are shown in Figure 11. Brazing for 2 min produced a continuous Si<sub>3</sub>Ti<sub>5</sub> layer up to ~2 µm thick on the Al<sub>2</sub>O<sub>3</sub>, occasionally with a number of CuSiTi particles with a typical composition of 12Cu–11Ni–10Fe–2Co–32Si–33Ti at.% alongside the Si<sub>3</sub>Ti<sub>5</sub> layer. Increasing  $\tau$  to 15 min broke down the Si<sub>3</sub>Ti<sub>5</sub> layer significantly and produced a variation in the microstructure at the ABA/Al<sub>2</sub>O<sub>3</sub> interface. No Si<sub>3</sub>Ti<sub>5</sub> was observed at various positions along this interface. When Si<sub>3</sub>Ti<sub>5</sub> was observed, it was either in the form of a 450 nm thick broken layer or as individual particles similar in width. CuSiTi particles were also observed at the ABA/Al<sub>2</sub>O<sub>3</sub> interface, but not consistently across the interface. No evidence of Si<sub>3</sub>Ti<sub>5</sub> was found after increasing  $\tau$ further. Instead, individual CuSiTi particles were occasionally observed along the ABA/Al<sub>2</sub>O<sub>3</sub> interface.

## 3.1.3. Brazing 95 wt.% Al<sub>2</sub>O<sub>3</sub> at 1075 °C

BSEIs of cross-sections of 95 wt.%  $Al_2O_3$ -Kovar<sup>®</sup> joints that were held at 1075 °C for 2 to 45 min are shown in Figure 12. In a joint brazed for 2 min, the Ni<sub>16</sub>Si<sub>7</sub>Ti<sub>6</sub>, Fe<sub>2</sub>Ti and CuSiTi phases were typically observed closer to the centre of the ABA. The quantity of CuSiTi reduced to produce more Fe<sub>2</sub>Ti, with the remaining CuSiTi typically positioned within the newly formed Fe<sub>2</sub>Ti. Ni<sub>16</sub>Si<sub>7</sub>Ti<sub>6</sub> was consistently

observed between the Fe<sub>2</sub>Ti and the ABA, and so Ni<sub>16</sub>Si<sub>7</sub>Ti<sub>6</sub> completely surrounded the Fe<sub>2</sub>Ti phase. In the same joint, large single particles with a typical composition of 23Ni–18Fe–12Co–5Cu–22Si–20Ti at.% were observed on the Al<sub>2</sub>O<sub>3</sub>. The crystal structure of these particles was identified by electron diffraction as that of Ni<sub>16</sub>Si<sub>7</sub>Ti<sub>6</sub> (cubic,  $Fm\overline{3}m$ , space group 225) with the lattice parameter a = 11.7 Å. The EDS measurements are consistent with a solid solution of Fe, Co, Cu and Al in Ni<sub>16</sub>Si<sub>7</sub>Ti<sub>6</sub>.

Brazing for 15 min produced a 600 nm thick  $Ni_{16}Si_7Ti_6$  layer on the  $Al_2O_3$ , which was almost continuous across the entire length of the ABA/Al\_2O\_3 interface. Several individual  $Ni_{16}Si_7Ti_6$  particles were also observed in the ABA alongside this  $Ni_{16}Si_7Ti_6$ layer. No evidence of CuSiTi was found at the ABA/Al\_2O\_3 interface in any joint brazed at 1075 °C. At this point, the Fe<sub>3</sub>Si layer on the Kovar<sup>®</sup> was partly broken, and so particles of Fe<sub>3</sub>Si were found scattered throughout the ABA. The extent to which the Fe<sub>3</sub>Si layer broke down varied across the joint, but a continuous Fe<sub>3</sub>Si layer of at least 1.0 µm in width was typically observed on the Kovar<sup>®</sup>. In a joint brazed for 30 min, the Fe<sub>3</sub>Si on the Kovar<sup>®</sup> was in the form of a very thin layer between ~50 nm and ~400 nm. The  $Ni_{16}Si_7Ti_6$  layer on the  $Al_2O_3$  became thicker by extending  $\tau$  to 30 min, ranging from 0.5 to 2 µm. This layer was also partly broken, leaving several  $Ni_{16}Si_7Ti_6$ particles alongside the  $Ni_{16}Si_7Ti_6$  layer. A 3 µm thick  $Ni_{16}Si_7Ti_6$  layer developed on the  $Al_2O_3$  in a joint brazed for 45 min. In the same joint, the Fe<sub>3</sub>Si layer on the Kovar<sup>®</sup> was typically in the form of a very thin layer. At some parts of this joint the ABA separated from the Kovar<sup>®</sup> to leave voids at the ABA/Kovar<sup>®</sup> interface.

## 3.2. Brazing 99.7 wt.% Al<sub>2</sub>O<sub>3</sub> to Kovar<sup>®</sup>

The ABA did not bond chemically to 99.7 wt.%  $Al_2O_3$  using a  $T_p$  of 1025 °C and  $\tau$  ranging from 2 to 45 min; a BSEI of a cross-section of a joint that was brazed for 15 min is shown in Figure 13. This is because a very low level of silica-based secondary phase is present in the  $Al_2O_3$ . Notwithstanding the silicon present in the molten braze, the lack of a ready supply of silicon from the alumina has prevented the formation of a clearly identifiable Si<sub>3</sub>Ti<sub>5</sub> layer at the  $Al_2O_3$ -braze interface. Close inspection of the  $Al_2O_3$ -braze interface shows some evidence of contrast consistent with the formation

of  $Si_3Ti_5$ , but it is evident that any interfacial reaction product is insignificant in comparison with that found on the 95 wt%  $Al_2O_3$ . As a consequence of the relative absence of this chemical reaction at the ABA/ $Al_2O_3$  interface, some of the ABA flowed out of these joints.

#### 4. Discussion

Joints containing a near-continuous  $1.5-2.5 \ \mu m$  thick  $Si_3Ti_5$  layer on the  $Al_2O_3$  and a continuous Fe<sub>3</sub>Si layer on the Kovar<sup>®</sup> did not break apart on handling and could be prepared easily for microscopy. These joints were made with 95 wt.%  $Al_2O_3$  and brazed at a  $T_p$  of 1025 °C for 0–45 min or at 1050 °C for 2 min. In a recent study [2], both alumina ceramics used in this work were brazed to themselves using a Ag–Cu–Ti-based alloy also containing a relatively small quantity of titanium, ~1.8 wt.%. This alloy began to melt at ~780 °C and then it reacted with each alumina to form  $Ti_3Cu_3O$  as the main interfacial phase. This oxide was found to be unstable at the brazing temperatures used, between 815 and 875 °C, and so it broke down, to different extents, with time at these temperatures, with the rate of this process accelerated greatly by increasing the brazing temperature.  $Ti_3Cu_3O$  was not observed in the joints made using Copper ABA<sup>®</sup> probably because it is highly unstable at temperatures equal to or greater than the liquidus temperature of Copper ABA<sup>®</sup> (i.e. the lowest brazing temperature that can be used for this ABA).

Despite the silicon in the molten braze, it is apparent from a comparison of Figures 2 and 13 that  $SiO_2$  present in the grain boundaries of the 95 wt%  $Al_2O_3$  is the dominant contributor to the formation of  $Si_3Ti_5$  at the interface with 95 wt%  $Al_2O_3$ . This formation of  $Si_3Ti_5$  on the 95 wt.%  $Al_2O_3$  can be described by the schematic equation

$$\frac{5}{3}\operatorname{Ti} + \operatorname{SiO}_2 \longrightarrow \frac{1}{3}\operatorname{Si}_3\operatorname{Ti}_5 + 2\operatorname{O}$$
(1)

indicating that Ti diffuses to the alumina when the ABA melts to react with the  $SiO_2$  in the alumina. Although  $Si_3Ti_5$  can accommodate up to ~10 at.% O at 1100 °C [22], no appreciable amount of oxygen was identified in this phase. It is likely that the oxygen liberated by this reaction is dissolved into the ABA. The Al<sub>2</sub>O<sub>3</sub>-braze interface would seem to act as an efficient site for heterogeneous nucleation of Si<sub>3</sub>Ti<sub>5</sub>, so that when

there is a ready supply of silicon from the  $Al_2O_3$  to dissolve into the molten braze, there will be a strong chemical reaction to form a near-continuous  $Si_3Ti_5$  layer. In the absence of an additional ready supply of silicon from the  $Al_2O_3$ , the  $Si_3Ti_5$  formed at the  $Al_2O_3$ -braze interface is insignificant, as is seen in the brazing of the 99.7 wt%  $Al_2O_3$  to Kovar using Copper ABA.

Other Si–Ti compounds such as SiTi and Si<sub>2</sub>Ti were not identified at the ABA/Al<sub>2</sub>O<sub>3</sub> interface. These Si–Ti compounds are thermodynamically less likely to form than Si<sub>3</sub>Ti<sub>5</sub> at temperatures between 1025 and 1050 °C; the Gibbs free energies of formation per mole Si at 1300 K for SiTi, Si<sub>2</sub>Ti and Si<sub>3</sub>Ti<sub>5</sub> are –129, –63 and –196 kJ mol<sup>-1</sup>, respectively [23]. Si<sub>3</sub>Ti<sub>5</sub> is not stable at 1025 and 1050 °C, and so it broke down chemically over time at these bonding temperatures. This decomposition of Si<sub>3</sub>Ti<sub>5</sub> occurred after 15 min at 1025 °C and after 2 min at 1050 °C. The formation of CuSiTi particles at the ABA/Al<sub>2</sub>O<sub>3</sub> interface near large pockets of SiO<sub>2</sub> in the Al<sub>2</sub>O<sub>3</sub> was very noticeable at 1050 °C. A possible explanation for the formation of CuSiTi is described by the schematic reaction:

$$Ti + Cu + SiO_2 \longrightarrow CuSiTi + 2O$$
 (2)

where the oxygen liberated is likely to be dissolved into the ABA because no appreciable amount of this element was identified in the CuSiTi. No CuSiTi was observed at the ABA/Al<sub>2</sub>O<sub>3</sub> interface using a  $T_p \ge 1075$  °C. Furthermore, only very small amounts of CuSiTi, which appear to develop originally at the ABA/Kovar<sup>®</sup> interface and then migrated into the ABA, were observed in a joint brazed at 1075 °C for 2 min. This phase disappeared at longer bonding times to produce more Fe<sub>2</sub>Ti in the ABA and enabled a Ni<sub>16</sub>Si<sub>7</sub>Ti<sub>6</sub> layer to form on the Al<sub>2</sub>O<sub>3</sub>.

It is apparent that some of the chemical elements of the CuSiTi found in the ABA, which includes significant quantities of Ni and Fe that are present by substitution of some of the Cu, diffuse to the ABA/Al<sub>2</sub>O<sub>3</sub> interface after the CuSiTi decomposes. These chemical elements subsequently react with the ceramic component to form  $Ni_{16}Si_7Ti_6$  on the Al<sub>2</sub>O<sub>3</sub>. It was not surprising that no evidence of plastic deformation of  $Ni_{16}Si_7Ti_6$  was observed in the TEM, such as dislocations, because this silicide has a highly ordered crystal structure with a large unit cell, as described in [24]. By the time

a continuous  $Ni_{16}Si_7Ti_6$  layer formed on the  $Al_2O_3$ , the Fe<sub>3</sub>Si layer on the Kovar<sup>w</sup> had broken down significantly. As a consequence, all of the joints brazed using a  $T_p$  of 1075 °C broke on handling.

At the ABA/Kovar<sup>®</sup> interface, the Fe<sub>3</sub>Si layer on the Kovar<sup>®</sup> forms very quickly and its thickness increases parabolically with time between 2 and 45 min at 1025 °C. The work of Mehrer et al. [25,26] shows that Fe diffuses much faster than Si through Fe<sub>3</sub>Si, and so a Fe<sub>3</sub>Si growth front may develop at the Fe<sub>3</sub>Si/ABA interface. The Ni<sub>16</sub>Si<sub>7</sub>Ti<sub>6</sub> in the ABA appears to form on the Fe<sub>3</sub>Si layer and then break away into the ABA. The chemical reactions leading to the formation of Ni<sub>16</sub>Si<sub>7</sub>Ti<sub>6</sub>, Fe<sub>2</sub>Ti and CuSiTi in the ABA are not clear.

Relatively few microstructural developments occurred at the ABA/Kovar<sup>®</sup> interface, compared with the ABA/Al<sub>2</sub>O<sub>3</sub> interface, as a function of  $\tau$  between 1025 and 1050 °C. The most significant change at the ABA/Kovar<sup>®</sup> interface was the breakdown of the Fe<sub>3</sub>Si layer at 1075 °C with bonding times  $\geq 15$  min, which eventually resulted in separation of the ABA from the Kovar<sup>®</sup>. This microstructural development further compounds the problems of brazing at high temperatures, which include leakage of the ABA and the formation of a non-continuous brittle silicide at the ABA/Al<sub>2</sub>O<sub>3</sub> interface.

The adhesion of the ABA to both the  $Al_2O_3$  and Kovar<sup>®</sup> depends on the formation of continuous, or near-continuous,  $Si_3Ti_5$  and  $Fe_3Si$  interfacial layers. The most appropriate brazing conditions to preserve a near-continuous  $Si_3Ti_5$  layer on the  $Al_2O_3$ and a continuous  $Fe_3Si$  layer on the Kovar<sup>®</sup> were found to be  $\tau \le 15$  min at a  $T_p$  of 1025 °C or  $\le 2$  min at 1050 °C. Other conditions produced very weak bonds as a consequence of the  $Si_3Ti_5$  and  $Fe_3Si$  layers breaking down. Further complications of brazing at a higher  $T_p$  include leakage of the ABA out of the joint and the formation of a new brittle silicide,  $Ni_{16}Si_7Ti_6$ , at the ABA/ $Al_2O_3$  interface. Based on the microstructural observations made, the ranges of suitable values for  $T_p$  and  $\tau$  to bond  $Al_2O_3$  to Kovar<sup>®</sup> using Copper ABA<sup>®</sup> are quite limited, as mentioned above. It is anticipated that using this ABA to prepare large joints would not be feasible. This is because these joints need to be held at the  $T_p$  used for several minutes to minimise any temperature gradients across the joint.

Modifying the composition of Copper ABA<sup>®</sup> by increasing the Ti content might improve the chemical interaction between the ABA and  $Al_2O_3$  by forming a thicker and continuous  $Si_3Ti_5$  layer (assuming that the liquidus temperature of the modified ABA is not raised to a temperature at which  $Si_3Ti_5$  is very unstable). This could possibly increase the maximum value of  $\tau$  that can be used at the liquidus temperature of the modified ABA, because it would take longer for the thicker  $Si_3Ti_5$  layer to break down. However, larger quantities of brittle phases at the ABA/Kovar<sup>®</sup> would also form because of the strong chemical interaction between the Kovar<sup>®</sup> and the Ti in the ABA.

After an investigation of the use of Zr as an active element to braze 94 wt.%  $Al_2O_3$  to Kovar<sup>®</sup> using 69Ag–92Cu–2Zr wt.%, Stephens et al. [27] reported that only a minor amount of Zr was consumed first in the chemical reactions between the ABA and Kovar<sup>®</sup>. As a consequence, the majority of the Zr in the ABA was available to react with the  $Al_2O_3$  to form a  $ZrO_2$  layer; images of the ABA/Kovar<sup>®</sup> interfaces or ABA/Al\_2O<sub>3</sub> interfaces of the joints are not provided in report of Stephens et al. [27]. A tentative conclusion from the work of Stephens et al. [27] is that Zr is less reactive compared to Ti at the ABA/Kovar<sup>®</sup> interface. If Zr is indeed relatively less reactive with Kovar<sup>®</sup>, it might be worthwhile to investigate other Zr-containing ABAs that can be used at high temperatures in service than more commonly used Ag–Cu–Ti-based ABAs.

#### **5.** Conclusions

The ability to bond  $Al_2O_3$  to Kovar<sup>®</sup> chemically using Copper ABA<sup>®</sup> has been investigated. The interfacial phases forming over a wide range of conditions have been identified and the effects of altering various brazing parameters, such  $T_p$  and  $\tau$ , on the resultant microstructure have been determined.

It was necessary to have a small amount of silica as a secondary phase in the  $Al_2O_3$ to bond the  $Al_2O_3$  component to the ABA chemically. This occurred in joints made at a  $T_p$  between 1025 and 1050 °C by a reaction between Ti in the ABA and the silica to produce a layer of Si<sub>3</sub>Ti<sub>5</sub> at the ABA/Al<sub>2</sub>O<sub>3</sub> interface. These joints also contained a layer of Fe<sub>3</sub>Si on the Kovar<sup>®</sup>, along with Ni<sub>16</sub>Si<sub>7</sub>Ti<sub>6</sub>, Fe<sub>2</sub>Ti, and CuSiTi in the ABA, near the ABA/Kovar<sup>®</sup> interface, either in the form of a layered structure or a collection of individual particles. The Si<sub>3</sub>Ti<sub>5</sub> layer broke down between 1025 and 1050 °C as a function of  $\tau$ . In order to preserve a near-continuous Si<sub>3</sub>Ti<sub>5</sub> layer on the Al<sub>2</sub>O<sub>3</sub>, and also a continuous Fe<sub>3</sub>Si layer on the Kovar<sup>®</sup>, brazing conditions of  $\tau \leq 15$  min at a  $T_p$  of 1025 °C or  $\leq 2$  min at 1050 °C were suitable. All joints prepared at a  $T_p \geq 1050$  °C with  $\tau > 2$  min broke apart on handling. This is because the Si<sub>3</sub>Ti<sub>5</sub> layer on the Al<sub>2</sub>O<sub>3</sub> broke down almost completely, to be replaced eventually by the brittle silicide Ni<sub>16</sub>Si<sub>7</sub>Ti<sub>6</sub> at 1075 °C, and the Fe<sub>3</sub>Si layer on the Kovar<sup>®</sup> also broke down.

The ABA/Al<sub>2</sub>O<sub>3</sub> interface is very sensitive to changes to the brazing cycle, particularly the  $T_p$  used. The degree of adhesion of the ABA to the Al<sub>2</sub>O<sub>3</sub> depends on the formation of a Si<sub>3</sub>Ti<sub>5</sub> interfacial layer, which requires some siliceous phase to be present at the surface of the Al<sub>2</sub>O<sub>3</sub>. If very high purity Al<sub>2</sub>O<sub>3</sub> has to be used with Copper ABA<sup>®</sup>, the bonding surface of the Al<sub>2</sub>O<sub>3</sub> should be modified to introduce a siliceous phase, so that the ABA bonds to the Al<sub>2</sub>O<sub>3</sub> chemically. However, it has been shown that even using Al<sub>2</sub>O<sub>3</sub> containing silica as a secondary phase, it is not straightforward to join the Al<sub>2</sub>O<sub>3</sub> to Kovar<sup>®</sup> using this ABA.

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## **Figure Captions**

Figure 1. BSEIs of a cross-section of Copper ABA<sup>®</sup> captured after resting the ABA on a stainless steel support and mounting in an acrylic polymer.

Figure 2. BSEIs of cross-sections of 95 wt.% Al<sub>2</sub>O<sub>2</sub>/Copper ABA<sup>®</sup>/Kovar<sup>®</sup> joints that were held at 1025 °C for a) 0 min, b) 2 min, c) 15 min, d) 30 min and e) 45 min. Figure 3. a) TEM bright field image of Si<sub>3</sub>Ti<sub>5</sub> particles at the ABA/Al<sub>2</sub>O<sub>3</sub> interface in a 95 wt.%  $Al_2O_3$ -Kovar<sup>®</sup> joint that was held at 1025 °C for 0 min, along with electron diffraction patterns from  $Si_{3}Ti_{5}$  with the zone axes b)  $[2\overline{1}\overline{1}0]$ , c)  $[4\overline{2}\overline{2}3]$  and d)  $[2\overline{1}\overline{1}3]$ . Figure 4. BSEIs of a 95 wt.% Al<sub>2</sub>O<sub>3</sub>/Copper ABA<sup>®</sup>/Kovar<sup>®</sup> joint that was held at 1025 °C for a nominal 1 s before cooling which concentrate on a part of the joint where CuSiTi has formed next to a large quantity of silica in the  $Al_2O_3$ . Figure 5. Electron diffraction patterns from CuSiTi found at the ABA/Al<sub>2</sub>O<sub>3</sub> interface in a 95 wt.% Al<sub>2</sub>O<sub>3</sub>-Kovar<sup>®</sup> joint that was held at 1025 °C for 0 min, with the zone axes a) [021], b) [011] and c) [001]. h00 reflections where h = 2n+1 are present in the [021] and [011] patterns as a consequence of double diffraction. Figure 6. a) TEM bright field image of a  $\text{Fe}_3\text{Si}$  layer at the ABA/Kovar<sup>®</sup> interface in a 95 wt.%  $Al_2O_3$ -Kovar<sup>®</sup> joint that was held at 1025 °C for 0 min, along with electron diffraction patterns from Fe<sub>3</sub>Si with the zone axes a) [010], b) [011] and c) [111]. Figure 7. a) TEM bright field image of  $Ni_{16}Si_7Ti_6$  found near the ABA/Kovar<sup>®</sup> interface in a 95 wt.% Al<sub>2</sub>O<sub>3</sub>-Kovar<sup>®</sup> joint that was held at 1025 °C for 0 min, along with electron diffraction patterns from  $Ni_{16}Si_7Ti_6$  with the zone axes a) [111], b) [112] and c) [001].

Figure 8. Electron diffraction patterns from  $\text{Fe}_2\text{Ti}$  found near the ABA/Kovar<sup>®</sup> interface in a 95 wt.%  $\text{Al}_2\text{O}_3$ -Kovar<sup>®</sup> joint that was held at 1025 °C for 0 min, with the zone axes a) [0001], b) [11 $\overline{2}$ 6] and c) [11 $\overline{2}$ 3].

Figure 9. a) TEM bright field images of a CuSiTi particle found near the ABA/Kovar<sup>®</sup> interface in a 95 wt.%  $Al_2O_3$ –Kovar<sup>®</sup> joint that was held at 1025 °C for 0 min; some of the dislocations in this particle are pinned to Cu inclusions. Electron diffraction patterns from CuSiTi are shown with the zone axes b) [010], c) [120] and d) [110].

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Figure 10. Thicknesses of the  $Fe_3Si$  layers formed in 95 wt.%  $Al_2O_3/Copper$ 

 $ABA^{(B)}/Kovar^{(B)}$  joints as a function of  $\tau^{\frac{1}{2}}$  for the different  $T_p$  used.

Figure 11. BSEIs of cross-sections of 95 wt.% Al<sub>2</sub>O<sub>3</sub>/Copper ABA<sup>®</sup>/Kovar<sup>®</sup> joints that

were held at 1050 °C for a) 2 min, b) 15 min, c) 30 min and d) 45 min.

Figure 12. BSEIs of cross-sections of 95 wt.%  $Al_2O_3/Copper ABA^{(B)}/Kovar^{(B)}$  joints that were held at 1075 °C for a) 2 min, b) 15 min, c) 30 min and d) 45 min.

Figure 13. BSEIs of a cross-section of a 99.7 wt.%  $Al_2O_3/Copper ABA^{(B)}/Kovar^{(B)}$  joint that was held at 1025 °C for 15 min.

Table 1. Chemical composition of the 95 wt.% and 99.7 wt.%  $Al_2O_3$  components used in wt.%. Average values from 30 electron microprobe measurements with errors of  $\pm$ one standard deviation reported. \*The quantities of these elements were below or approximately equal to the detection limit.

Al <sub>2</sub> O <sub>3</sub> purity/ wt.% Al <sub>2</sub> O <sub>3</sub>	Al	0	Si	Na	Mg	Ca	Fe	Zr
99.7	55.4 +1.3	44.0	0.2	0.0*	0.3	0.0*	0.0*	0.0*
95	52.2 +1.9	43.5	2.5 +0.4	0.3	0.4 + 0.2	0.6	0.2	0.3
	±1.7	±1.0	-0.1	±0.1	±0.2	±0.2	±0.1	±0.1

Table 2.  $T_p$  and  $\tau$  used to braze 95 and 99.7 wt.%  $Al_2O_3$ . \*Joints made with 95 wt.%  $Al_2O_3$  using these conditions and all joints made with 99.7 wt.%  $Al_2O_3$  were mounted in clear resin before cutting out cross-sections to avoid detaching the  $Al_2O_3$  from

	1025 °C	1050 °C	1075 °C	1100 °C
0 min	95 wt.%	—	—	—
2 min	95 and 99.7 wt.%	95 wt.%	*95 wt.%	*95 wt.%
15 min	95 and 99.7 wt.%	*95 wt.%	*95 wt.%	—
30 min	95 and 99.7 wt.%	*95 wt.%	*95 wt.%	—
45 min	95 and 99.7 wt.%	*95 wt.%	*95 wt.%	—

## the ABA.



Figure 1. BSEIs of a cross-section of Copper ABA<sup>®</sup> captured after resting the ABA on a stainless steel support and mounting in an acrylic polymer.

a)  $\tau = 0 \min$ 



Figure 2. BSEIs of cross-sections of 95 wt.% Al<sub>2</sub>O<sub>3</sub>/Copper ABA<sup>®</sup>/Kovar<sup>®</sup> joints that were held at 1025 °C for a) 0 min, b) 2 min, c) 15 min, d) 30 min and e) 45 min.



Figure 3. a) TEM bright field image of  $Si_3Ti_5$  particles at the ABA/Al<sub>2</sub>O<sub>3</sub> interface in a 95 wt.% Al<sub>2</sub>O<sub>3</sub>-Kovar<sup>®</sup> joint that was held at 1025 °C for 0 min, along with electron diffraction patterns from  $Si_3Ti_5$  with the zone axes b) [2110], c) [4223] and d) [2113].



Figure 4. BSEIs of a 95 wt.% Al<sub>2</sub>O<sub>3</sub>/Copper ABA<sup>®</sup>/Kovar<sup>®</sup> joint that was held at 1025 °C for a nominal 1 s before cooling which concentrate on a part of the joint where CuSiTi has formed next to a large quantity of silica in the Al<sub>2</sub>O<sub>3</sub>.



Figure 5. Electron diffraction patterns from CuSiTi found at the ABA/Al<sub>2</sub>O<sub>3</sub> interface in a 95 wt.% Al<sub>2</sub>O<sub>3</sub>–Kovar<sup>®</sup> joint that was held at 1025 °C for 0 min, with the zone axes a) [021], b) [011] and c) [001]. *h*00 reflections where h = 2n+1 are present in the [021] and [011] patterns as a consequence of double diffraction.



Figure 6. a) TEM bright field image of a Fe<sub>3</sub>Si layer at the ABA/Kovar<sup>®</sup> interface in a 95 wt.% Al<sub>2</sub>O<sub>3</sub>–Kovar<sup>®</sup> joint that was held at 1025 °C for 0 min, along with electron diffraction patterns from Fe<sub>3</sub>Si with the zone axes a) [010], b) [011] and c) [111].



Figure 7. a) TEM bright field image of a  $Ni_{16}Si_7Ti_6$  layer found near the ABA/Kovar<sup>®</sup> interface in a 95 wt.%  $Al_2O_3$ -Kovar<sup>®</sup> joint that was held at 1025 °C for 0 min, along with electron diffraction patterns from  $Ni_{16}Si_7Ti_6$  with the zone axes a) [111], b) [112] and c) [001].



Figure 8. Electron diffraction patterns from Fe<sub>2</sub>Ti found near the ABA/Kovar<sup>®</sup> interface in a 95 wt.%  $Al_2O_3$ -Kovar<sup>®</sup> joint that was held at 1025 °C for 0 min, with the zone axes a) [0001], b) [1126] and c) [1123].



Figure 9. a) TEM bright field images of a CuSiTi particle found near the ABA/Kovar<sup>®</sup> interface in a 95 wt.% Al<sub>2</sub>O<sub>3</sub>–Kovar<sup>®</sup> joint that was held at 1025 °C for 0 min; some of the dislocations in this particle are pinned to Cu inclusions. Electron diffraction patterns from CuSiTi are shown with the zone axes b) [010], c) [120] and d) [110].



Figure 10. Thicknesses of the Fe<sub>3</sub>Si layers formed in 95 wt.% Al<sub>2</sub>O<sub>3</sub>/Copper ABA<sup>®</sup>/Kovar<sup>®</sup> joints as a function of  $\tau^{\frac{1}{2}}$  for the different  $T_p$  used.



Figure 11. BSEIs of cross-sections of 95 wt.% Al<sub>2</sub>O<sub>3</sub>/Copper ABA<sup>®</sup>/Kovar<sup>®</sup> joints that were held at 1050 °C for a) 2 min, b) 15 min, c) 30 min and d) 45 min.



Figure 12. BSEIs of cross-sections of 95 wt.% Al<sub>2</sub>O<sub>3</sub>/Copper ABA<sup>®</sup>/Kovar<sup>®</sup> joints that were held at 1075 °C for a) 2 min, b) 15 min, c) 30 min and d) 45 min.



Figure 13. BSEIs of a cross-section of a 99.7 wt.% Al<sub>2</sub>O<sub>3</sub>/Copper ABA<sup>®</sup>/Kovar<sup>®</sup> joint that was held at 1025 °C for 15 min.